

Spec. No.: H5060-3P090B-NNNN

Issued Date: 2018-11-09

SPECIFICATION

Model Name: Detector

Model NO. : HL5060-3P090B

Customer No.:

Prepared by: Judy

Approved by: Xie Zhong Wu

Customer approved by: _____



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Detector

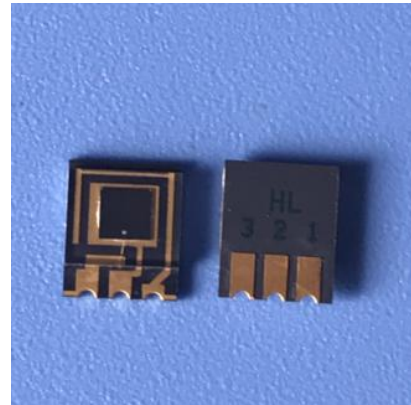
HL5060-3P090B

■Features

- Especially suitable for applications of 940nm.
- Short switching time

■Applications

- SPO2
- Optical module
- IR Remote controls of various equipment



Name	Model No.	Chip Size		Package
Detector	HL5060-3P090B	5.25mm ²	2.29mm×2.29mm	3-Pin, COB

■Absolute Maximum Ratings at Ta=25℃

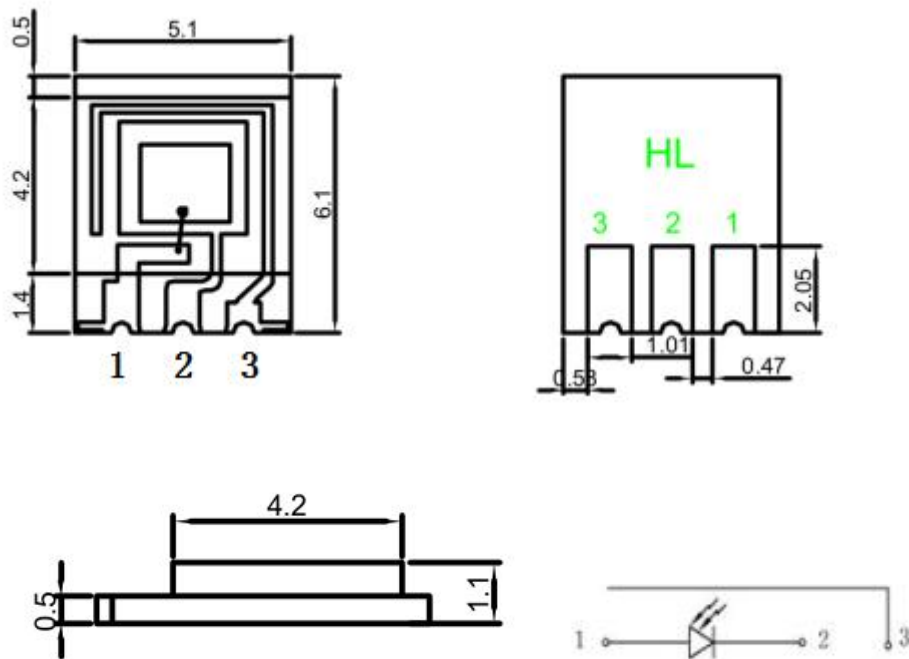
Parameter 参数	symbol 符号	Max.最大值	unit 单位	Note 备注
Operating Temperature	T _{opr}	-25~+85	℃	---
Storage Temperature	T _{Stg}	-40~+100	℃	---
Soldering Temperature	T _{S01}	≤260	℃	260℃ for 5 Seconds (260 度小于等于 5 秒)

■Electrical / Optical Characteristics at TA=25℃

Parameter(参数)	Symbol	Min.	Typ.	Max.	Units	Test Conditions
	符号	最小值	规格值	最大值	单位	测试条件
Forward Voltage	V _F	0.5	--	1.3	V	IF=20mA,H=0
Reverse Breakdown Voltage	V _{BR}	35	--	--	V	IR=100uA,H=0
Reverse Dark Current	I _D	--	--	20	nA	VR=10V,H=0
Light current	I _L	--	135	--	uA	VR=5V,H as 1mw/cm2@940nm
Peak Sensing Wavelength	λ _p	--	940	--	nm	--
Spectral Bandwidth	Λ _{0.5}	400	--	1100	nm	--
Junction Capacitance	C _J	--	5	--	pF	VR=3V,H=0,F=1MHz

Note(1):Parallel Light of 1000lux illumination is applied by a tungsten lamp of 2856k

■ Dimension:



- Notes:** 1. All dimensions are in millimeters
2. Tolerances unless dimensions $\pm 0.1\text{mm}$

■ Storage and Soldering Condition

1. Do not open moisture proofs bag before the products are ready to use
2. Before opening the package, the LEDs should be kept at 30°C or less and 90% RH or less.
3. The LEDs should be used within a year.
4. After opening the package, the LEDs should be kept at 30°C or less and 70% RH or less.
5. The LEDs should be used within 168 hours (7 days) after opening the package.
6. If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: $60\pm 5^{\circ}\text{C}$ for 24 hours.
7. When soldering, do not put stress on the LEDs during heating.
8. After soldering, do not warp the circuit board
9. Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave tow seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.